COMPLIANT



Vishay Semiconductors

Half Bridge IGBT Power Module, 600 V, 50 A



PRIMARY CHARACTERISTICS					
V _{CES}	600 V				
I_C at $T_C = 80 ^{\circ}C$	50 A				
$V_{CE(on)}$ (typical) at $I_C = 50$ A, 25 °C	1.65 V				
Speed	8 kHz to 30 kHz				
Package	INT-A-PAK				
Circuit configuration	Half bridge				

FEATURES

- Low V_{CE(on)} trench IGBT technology
- 5 µs short circuit capability
- V_{CE(on)} with positive temperature coefficient
- Maximum junction temperature 175 °C
- · Low inductance case
- · Fast and soft reverse recovery antiparallel FWD
- Isolated copper baseplate using DCB (direct copper bonding) technology
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

TYPICAL APPLICATIONS

- UPS (uninterruptable power supply)
- Electronic welders
- Switching mode power supplies

DESCRIPTION

Vishay's IGBT power module provides ultra low conduction loss as well as short circuit ruggedness. It is designed for applications such as UPS and SMPS.

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C unless otherwise noted)					
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS	
Collector to emitter voltage	V _{CES}		600	V	
Gate to emitter voltage	V_{GES}		± 20	V	
Collector current	1	T _C = 25 °C	85		
Collector current I _C	T _C = 80 °C	50			
Pulsed collector current	I _{CM} ⁽¹⁾	t _p = 1 ms	100	Α	
Diode continuous forward current	I _F	T _C = 80 °C	50		
Diode maximum forward current	I _{FM} ⁽¹⁾	t _p = 1 ms	100		
Maximum power dissipation	P _D	T _J = 175 °C	208	W	
Short circuit withstand time	t _{SC}	T _C = 125 °C	5	μs	
RMS isolation voltage	V _{ISOL}	f = 50 Hz, t = 1 min	4000	V	

Note

(1) Repetitive rating: pulse width limited by maximum junction temperature

IGBT ELECTRICAL SPECIFICATIONS (T _C = 25 °C unless otherwise noted)							
PARAMETER	SYMBOL	SYMBOL TEST CONDITIONS		TYP.	MAX.	UNITS	
Collector to emitter breakdown voltage	V _{(BR)CES}	T _J = 25 °C	600	-	-		
Collector to emitter voltage	.,	$V_{GE} = 15 \text{ V}, I_{C} = 50 \text{ A}, T_{J} = 25 ^{\circ}\text{C}$	-	1.65	2.10] _v	
Collector to enlitter voltage	V _{CE(on)}	V _{GE} = 15 V, I _C = 50 A, T _J = 175 °C	-	2.05	-	\ \	
Gate to emitter threshold voltage	V _{GE(th)}	$V_{CE} = V_{GE}, I_{C} = 1.4 \text{ mA}, T_{J} = 25 ^{\circ}\text{C}$	4.0	4.9	6.5		
Collector cut-off current	I _{CES}	$V_{CE} = V_{CES}$, $V_{GE} = 0$ V, $T_{J} = 25$ °C	-	-	1.0	mA	
Gate to emitter leakage current	I _{GES}	$V_{GE} = V_{GES}$, $V_{CE} = 0$ V, $T_{J} = 25$ °C	-	-	400	nA	

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SWITCHING CHARACTERISTICS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Turn-on delay time	t _{d(on)}		-	58	-	ns ns
Rise time	t _r	1	-	31	-	
Turn-off delay time	t _{d(off)}	$V_{CC} = 300 \text{ V}, I_{C} = 50 \text{ A}, R_{g} = 3.3 \Omega,$	-	80	-	
Fall time	t _f	$V_{CC} = 300 \text{ V}, I_C = 50 \text{ A}, R_g = 3.3 \Omega, \\ V_{GE} = \pm 15 \text{ V}, T_J = 25 \text{ °C}$	-	100	-	
Turn-on switching loss	E _{on}	1	-	0.41	-	1
Turn-off switching loss	E _{off}	7	-	0.42	-	- mJ
Turn-on delay time	t _{d(on)}		-	64	-	ns ns
Rise time	t _r	$V_{CC} = 300 \text{ V}, I_{C} = 50 \text{ A}, R_{g} = 3.3 \Omega, \\ V_{GE} = \pm 15 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$	-	37	-	
Turn-off delay time	t _{d(off)}		-	90	-	
Fall time	t _f		-	117	-	
Turn-on switching loss	E _{on}		-	0.69	-	m l
Turn-off switching loss	E _{off}	1	-	0.69	-	- mJ
Input capacitance	C _{ies}		-	3.03	-	
Output capacitance	C _{oes}	$V_{GE} = 0 \text{ V}, V_{CE} = 30 \text{ V}, f = 1.0 \text{ MHz}$	-	0.25	-	nF
Reverse transfer capacitance	C _{res}	1	-	0.09	-	
SC data	I _{SC}	$t_p \leq 5~\mu s,~V_{GE} = 15~V,~T_J = 125~^{\circ}C,\\ V_{CC} = 360~V,~V_{CEM} \leq 600~V$	-	450	-	Α
Stray inductance	L _{CE}		-	-	30	nΗ
Module lead resistance, terminal to chip	R _{CC'+EE'}		-	0.75	-	mΩ

DIODE ELECTRICAL SPECIFICATIONS (T _C = 25 °C unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Forward voltage	V-	V _F I _F = 50 A	T _J = 25 °C	-	1.35	1.75	V
Torward voitage	٧F		T _J = 125 °C	-	1.37	ı	
Doverse recovery charge	0	$I_{F} = 50 \text{ A, } V_{R} = 300 \text{ V,}$ $R_{G} = 3.3 \Omega$ $V_{GE} = -15 \text{ V}$	T _J = 25 °C	-	2.3	-	
Reverse recovery charge	Q _{rr}		T _J = 125 °C	-	4.3	-	μC
Dook reverse reservery ourrent	I _{rr}		T _J = 25 °C	-	33	-	Α
Peak reverse recovery current			T _J = 125 °C	-	58	-	_ ^
Develope receiver an every	E _{rec}		T _J = 25 °C	-	0.56	-	mJ
Reverse recovery energy			T _J = 125 °C	-	1.11	-	1110

THERMAL AND MECHANICAL SPECIFICATIONS								
PARAMETER		SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Maximum junction temperatu	re range	TJ		-	-	175	°C	
Storage temperature range		T _{Stg}		-40	-	125	°C	
Junction to case	IGBT	В		-	-	0.72		
per ½ module	Diode	R _{thJC}		-	-	1.02	K/W	
Case to sink (Conductive great	se applied)	R _{thCS}		-	0.05	-		
Mounting torque			Power terminal screw: M5 2.5 to 5		2.5 to 5.0)	Nm	
			Mounting screw: M6		3.0 to 5.0)	INITI	
Weight			Weight of module	-	150	-	g	

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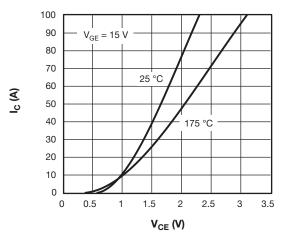


Fig. 1 - IGBT Typical Output Characteristics

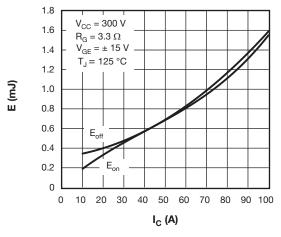


Fig. 2 - IGBT Transfer Characteristics

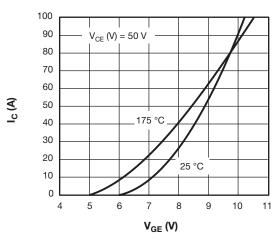


Fig. 3 - IGBT Switching Loss vs. I_C

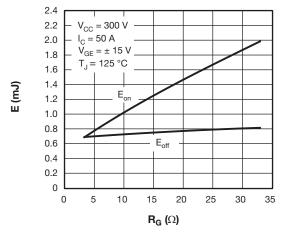
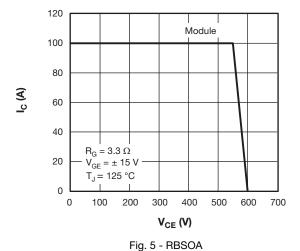


Fig. 4 - IGBT Switching Loss vs. R_G



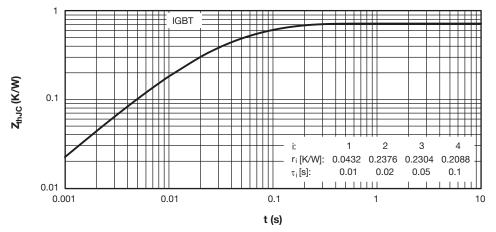


Fig. 6 - IGBT Transient Thermal Impedance

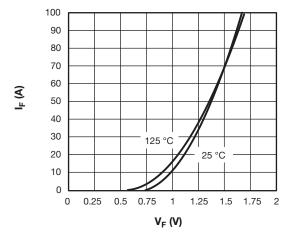


Fig. 7 - Diode Forward Characteristics

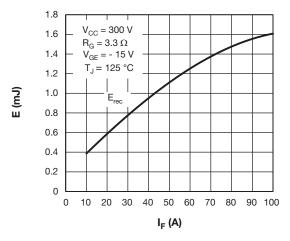


Fig. 8 - Diode Switching Loss vs. I_F

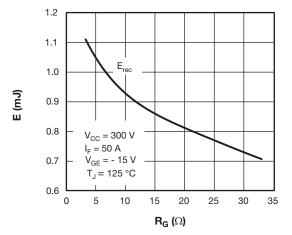


Fig. 9 - Diode Switching Loss vs. R_G

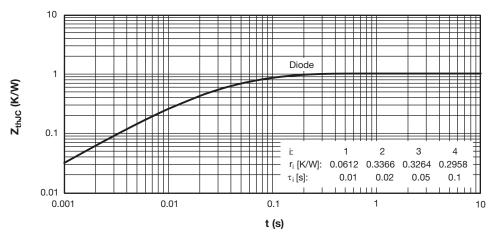
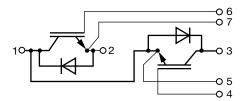


Fig. 10 - Diode Transient Thermal Impedance

CIRCUIT CONFIGURATION

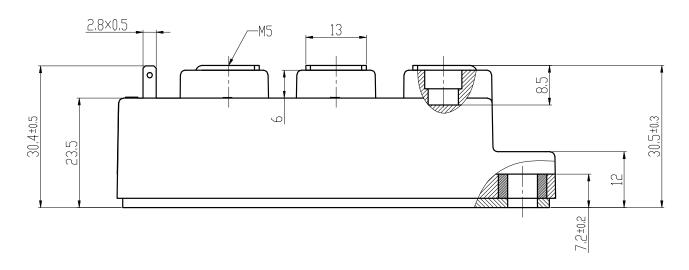


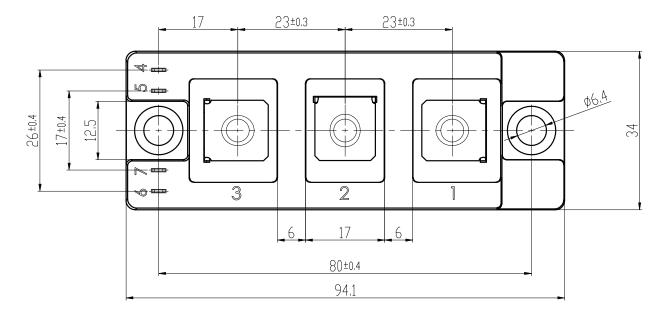
LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95524			



INT-A-PAK

DIMENSIONS in millimeters (inches)





Legal Disclaimer Notice



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